

EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR
ENCAPSULATION, AND SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT

Disclosed are an epoxy resin composition for semiconductor encapsulation containing (A) an epoxy resin, (B) a curing agent, (C) an inorganic filler material, (D) a hydrocarbon compound having structures of formula (1) and formula (2), and (E) a hydrocarbon compound having an ester group; and a semiconductor device including a semiconductor element encapsulated with the epoxy resin composition for semiconductor encapsulation.

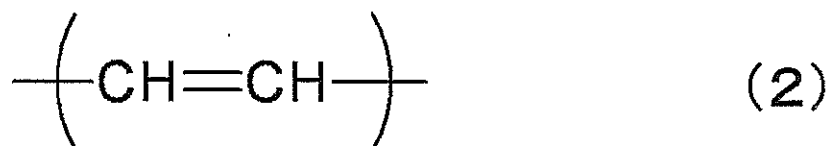
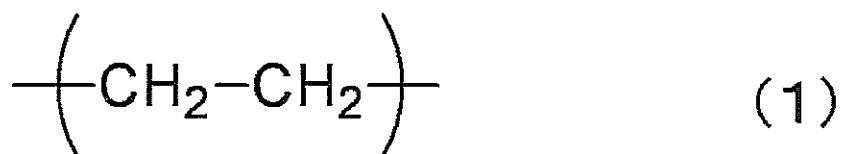


Figure 1 to accompany the abstract